



Toward Sustainable and Transparent Benchmarking for Academic Physical Design Research

Heterogeneous Integration, VLSI physical design, Benchmarking

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Outline

- 1 Introduction
- 2 Pin-3D Enablement and Flow
- 3 Pin-3D Validations
- 4 Key Takeaway



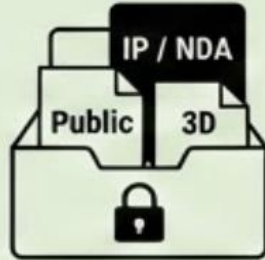
1

Introduction

2D and 3D Physical Design Research



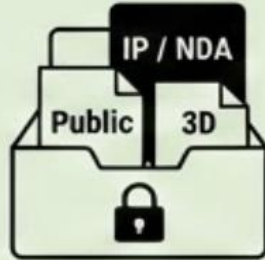
**Poor
Reproducibility**



Too Few Shareable Testcases

- Industrial testcases hard to share (IP / NDA)
- Public testcases limited in scale & diversity

Poor
Reproducibility



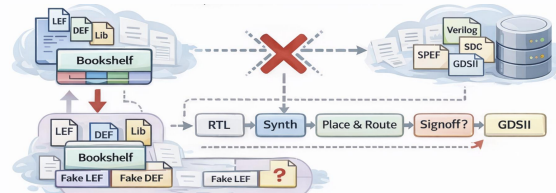
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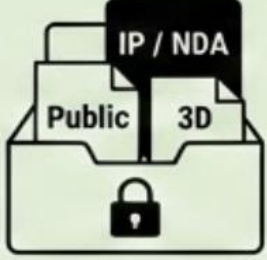
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Poor
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Format & Interface Fragmentation

- Academic testcases not standardized
- Interfaces across tools (bookshelf, fake lef, def)





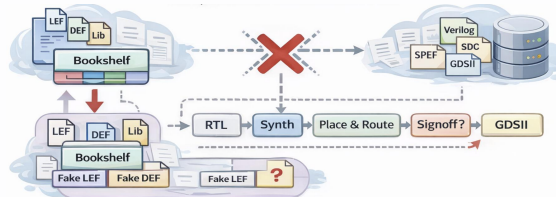
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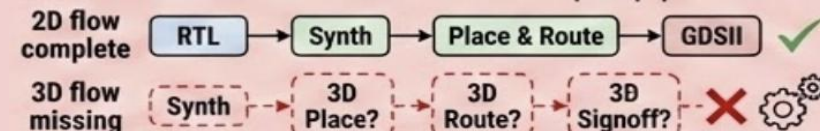
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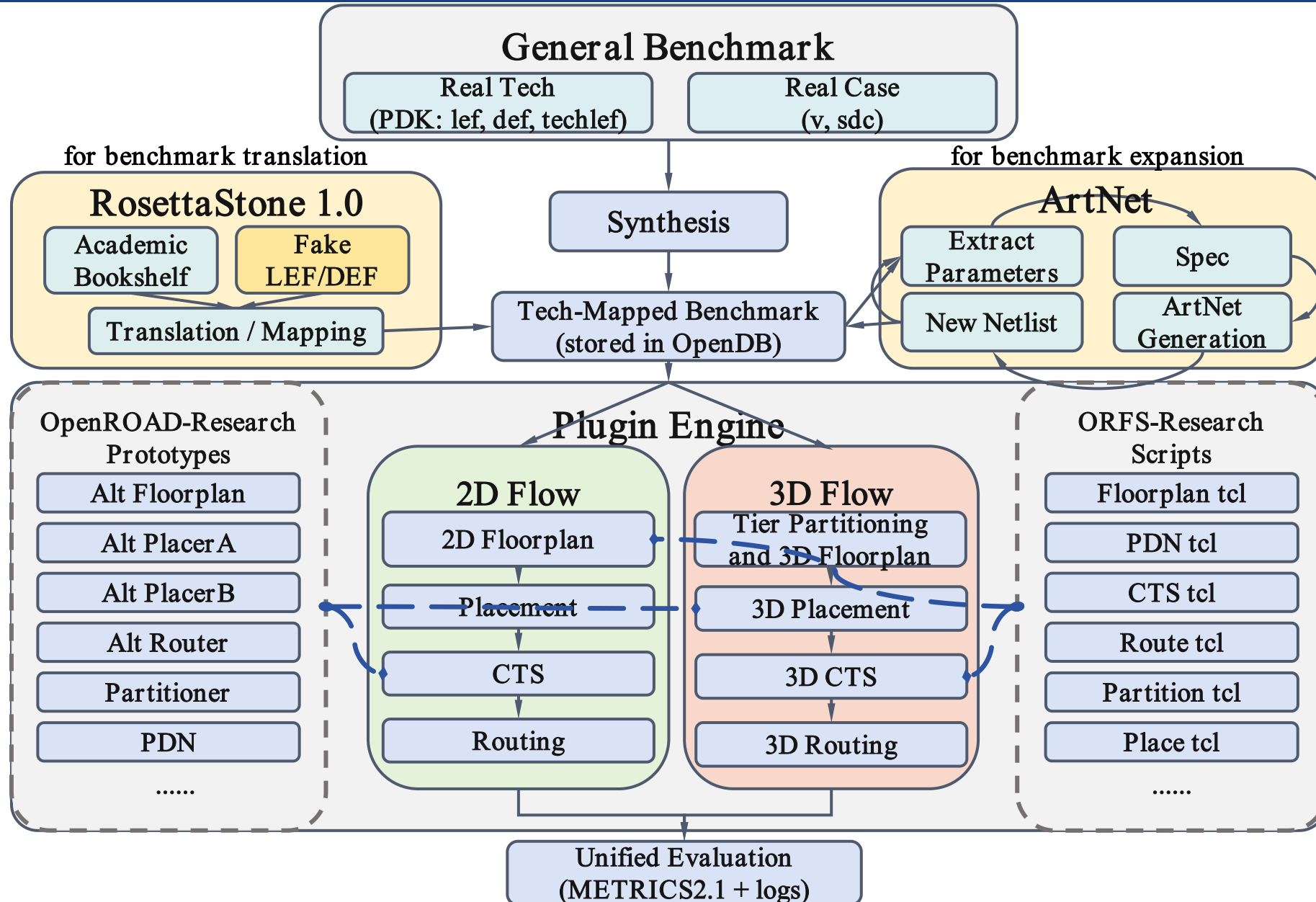


Flow Incompleteness & Evaluation

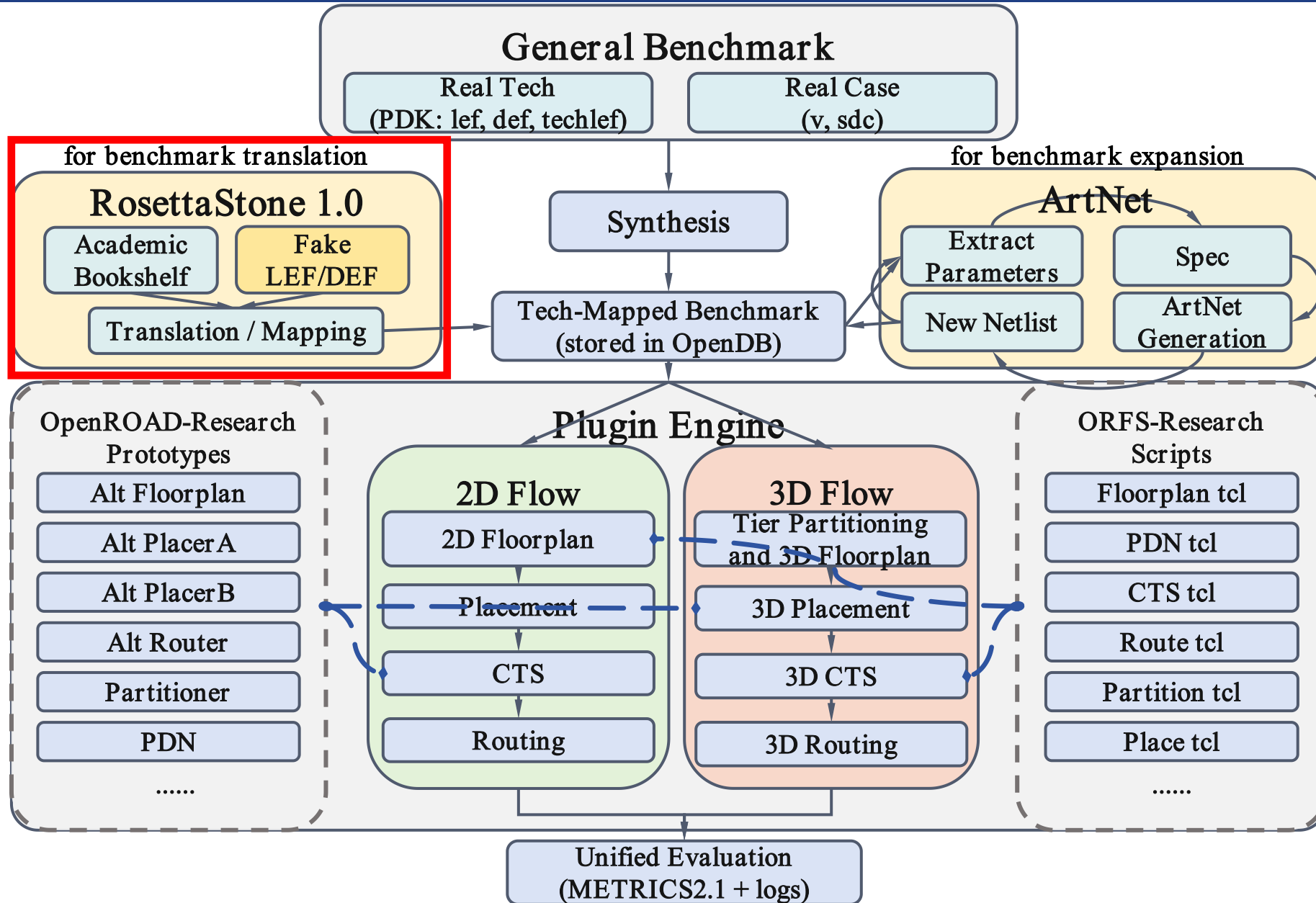
- Benchmark Inputs Incomplete (LEF/Lib/RC)
- End-to-end RTL-to-GDS flows often incomplete
- Metrics and reporting differ



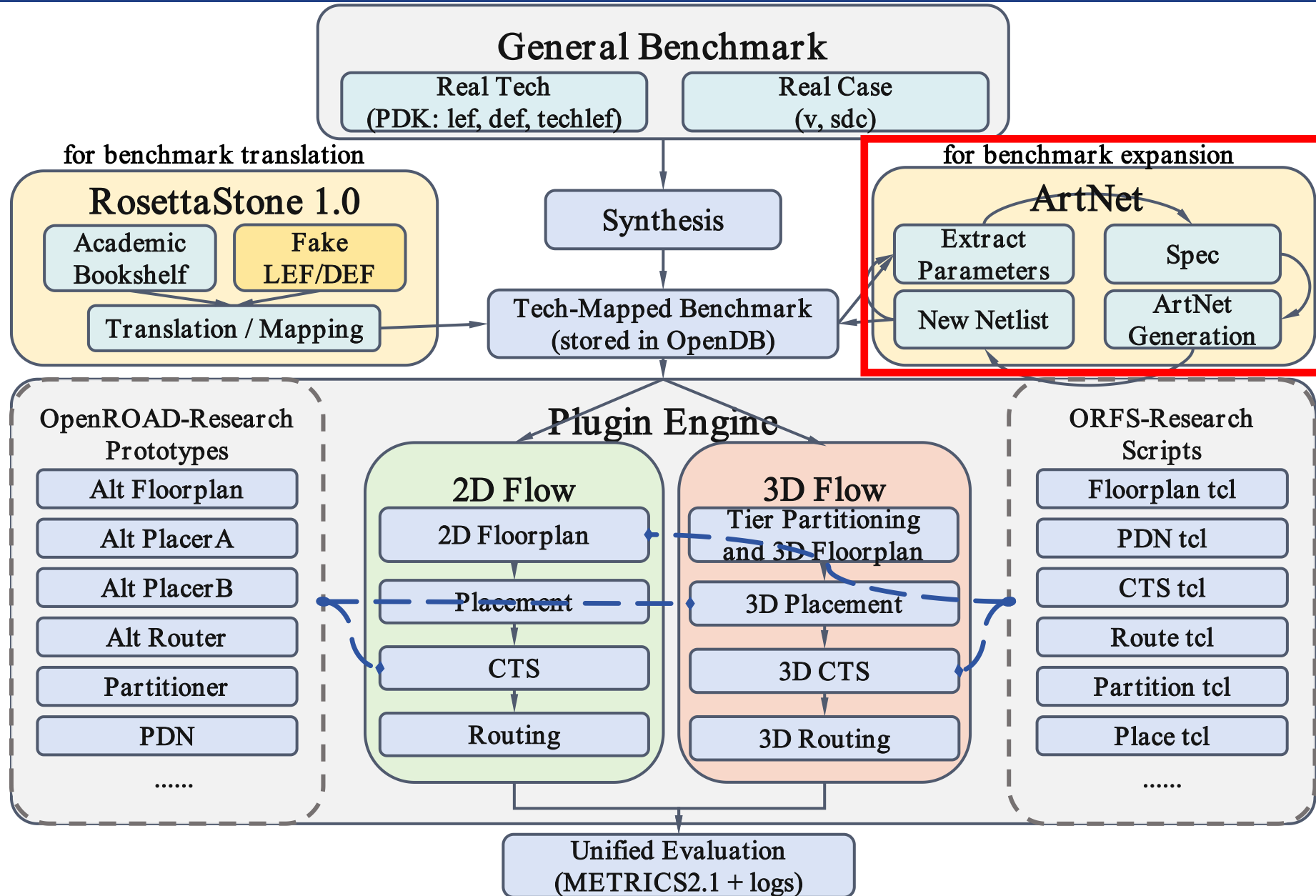
RosettaStone 2.0:



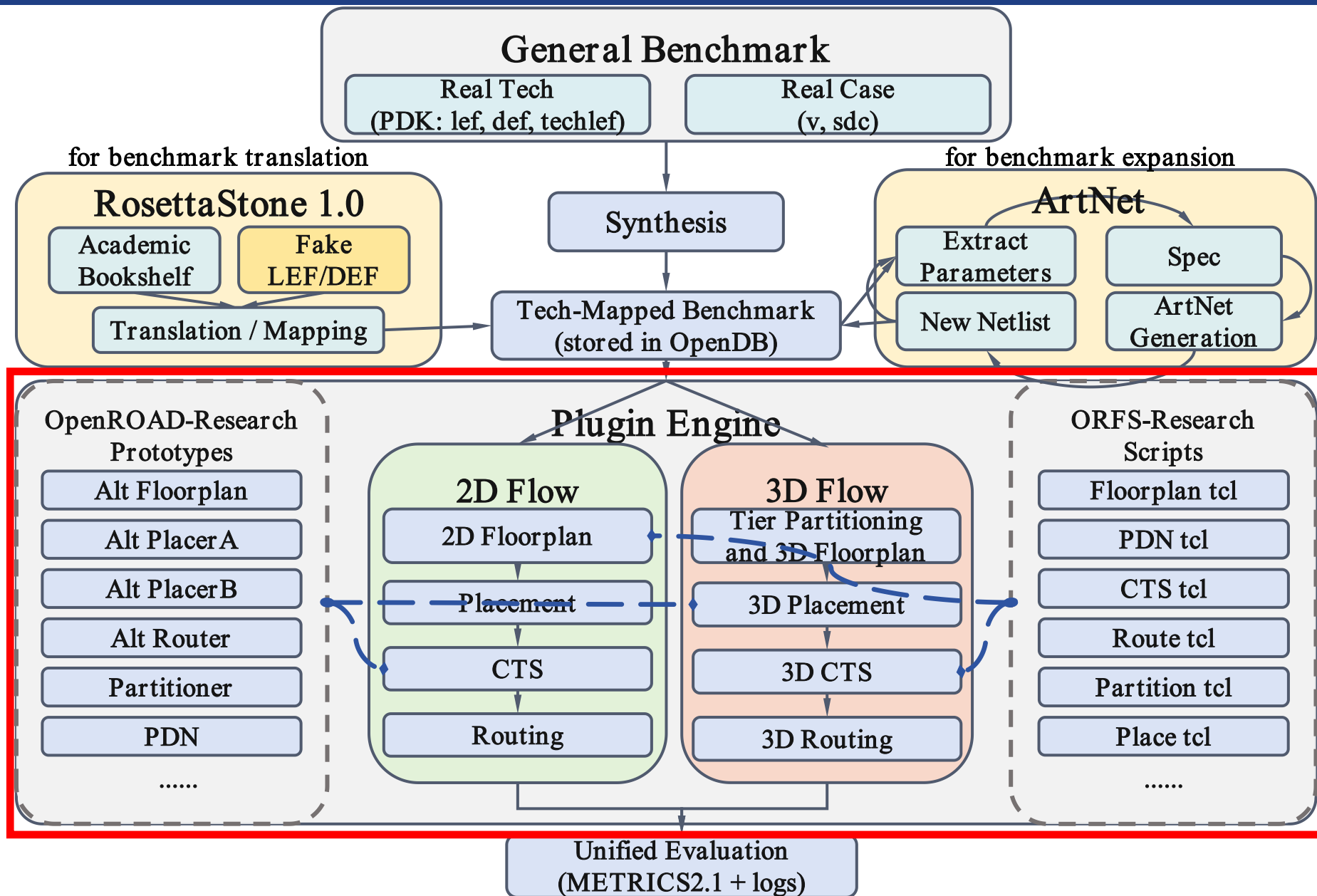
RosettaStone 2.0: backplane



RosettaStone 2.0: backplane



RosettaStone 2.0: backplane





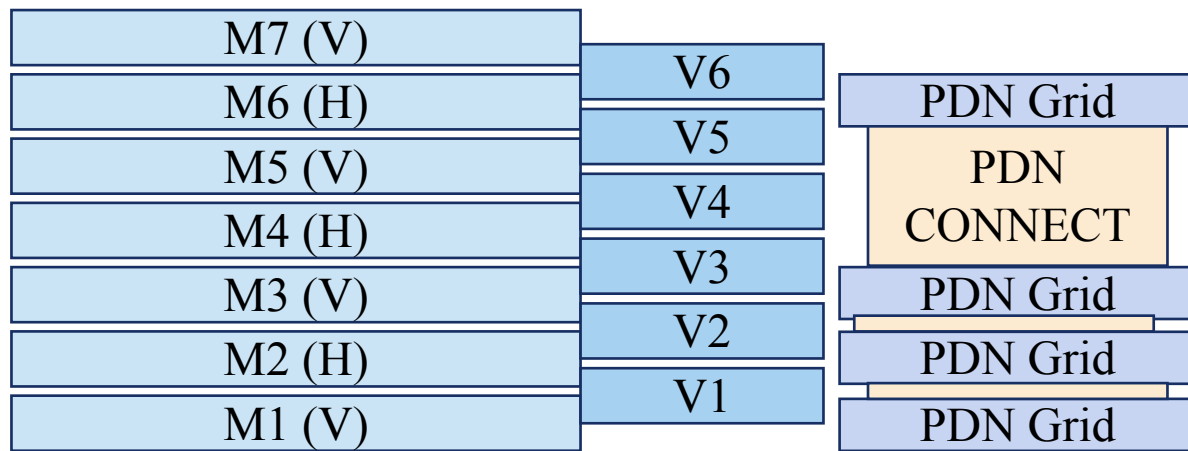
2

Pin-3D Enablement and Flow

Use 2D tools to implement 3D VLSI designs

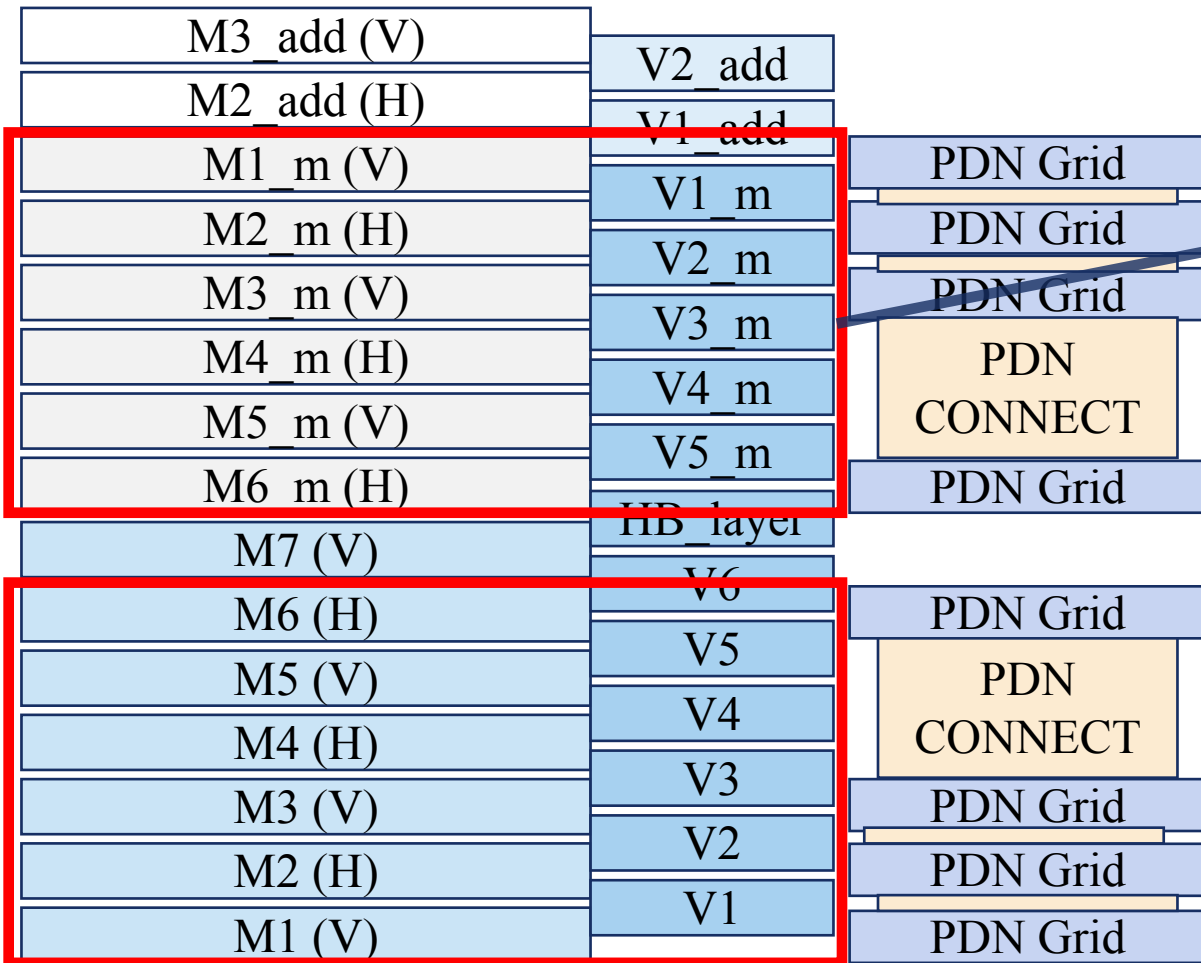


Homogeneous Integration: ASAP7 3D





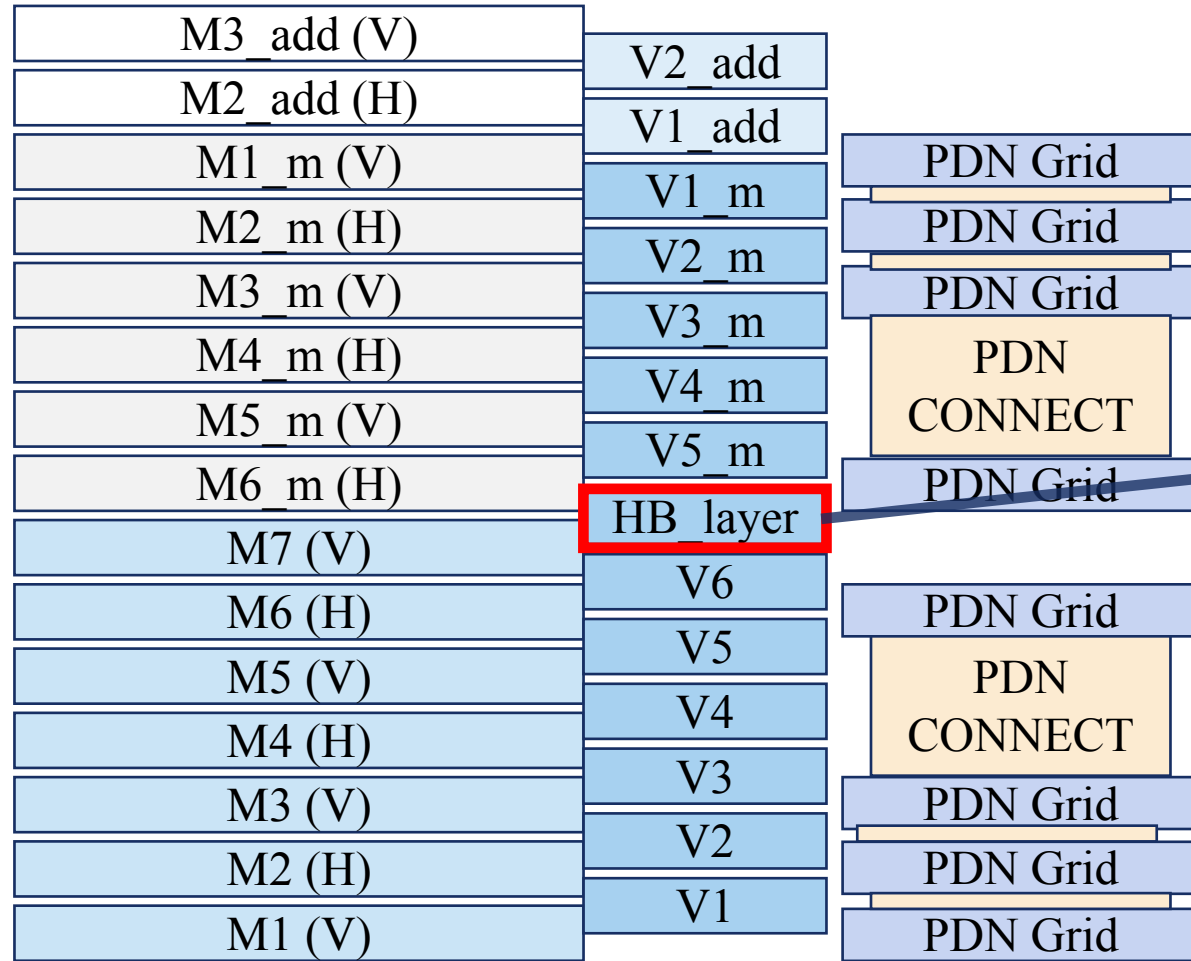
Homogeneous Integration: ASAP7 3D



Mirror the 2D metal stack with _m layers and _m vias to form a unified stack



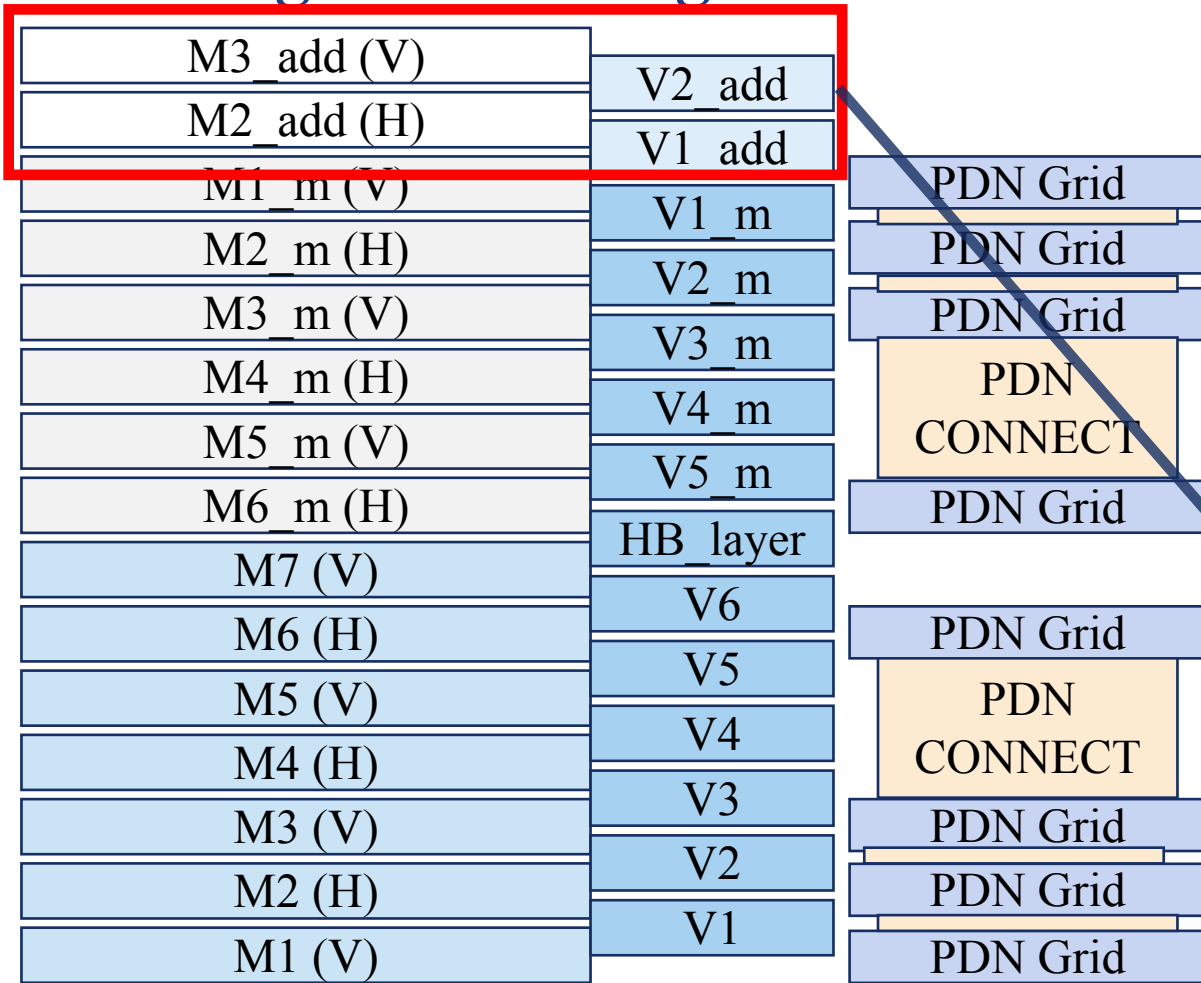
Homogeneous Integration: ASAP7 3D



**Model Hybrid Bonding
Terminals (HBTs) as vertical
vias on the HB layer**



Homogeneous Integration: ASAP7 3D



MAX_ROUTING_LAYER M2_m/M3_add
MIN_ROUTING_LAYER M2

For OpenROAD Tool specific pin access logic, we cannot set layer below M1_m for routing



Homogeneous Integration: ASAP7 3D

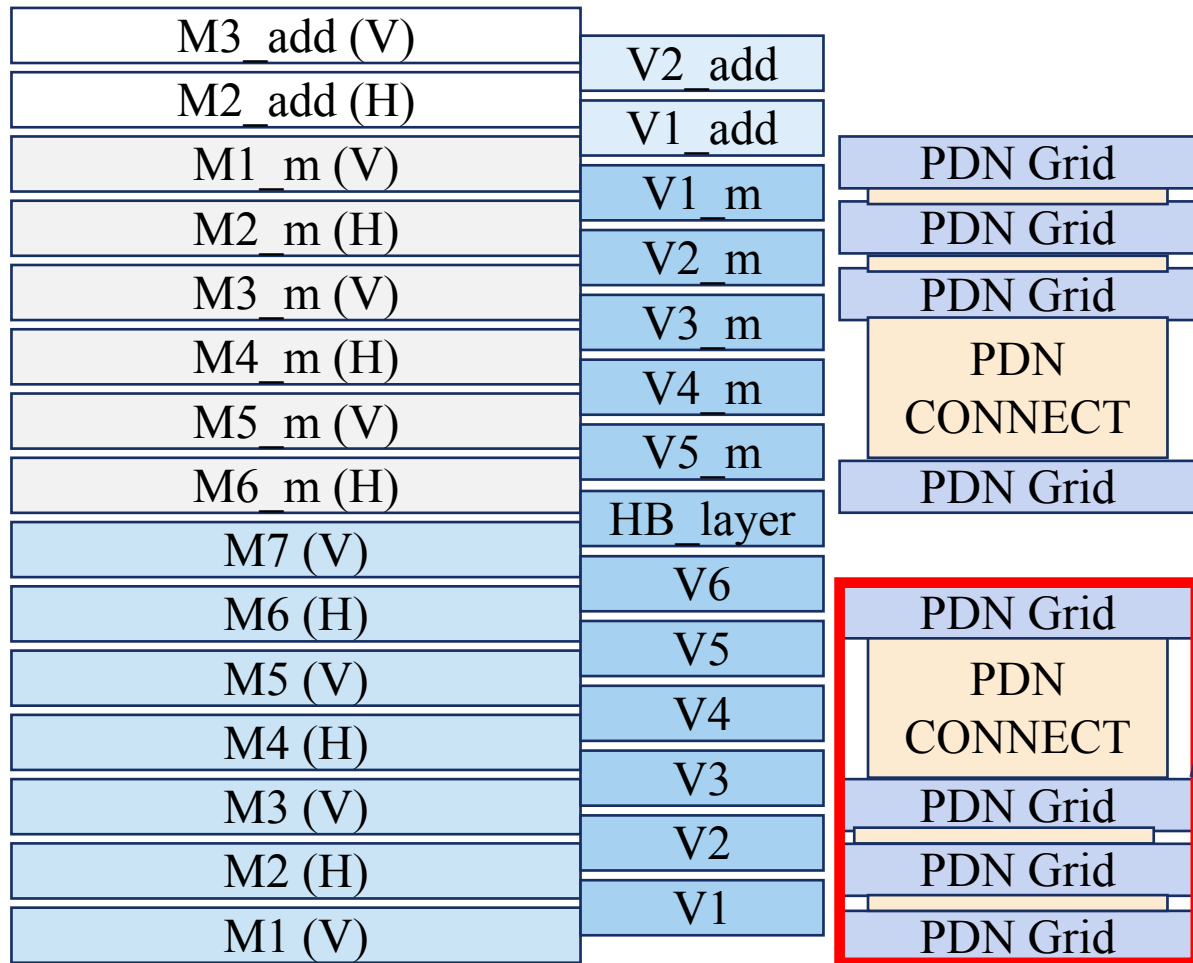
M3_add (V)	V2_add	
M2_add (H)	V1_add	
M1_m (V)	V1_m	PDN Grid
M2_m (H)	V2_m	PDN Grid
M3_m (V)	V3_m	PDN Grid
M4_m (H)	V4_m	PDN CONNECT
M5_m (V)	V5_m	PDN Grid
M6_m (H)	HB_layer	
M7 (V)	V6	PDN Grid
M6 (H)	V5	
M5 (V)	V4	PDN CONNECT
M4 (H)	V3	PDN Grid
M3 (V)	V2	PDN Grid
M2 (H)	V1	PDN Grid
M1 (V)		

Make 3D designs appear as one unified 13-layer routing environment to unmodified 2D engines

Pin-3D Enablement (2/2): How to optimize one tier?



Homogeneous Integration: ASAP7 3D



Use tier-specific PDN grids (BOT_VDD/VSS vs. TOP_VDD/VSS) to keep supplies isolated

Pin-3D Enablement (2/2): How to optimize one tier?

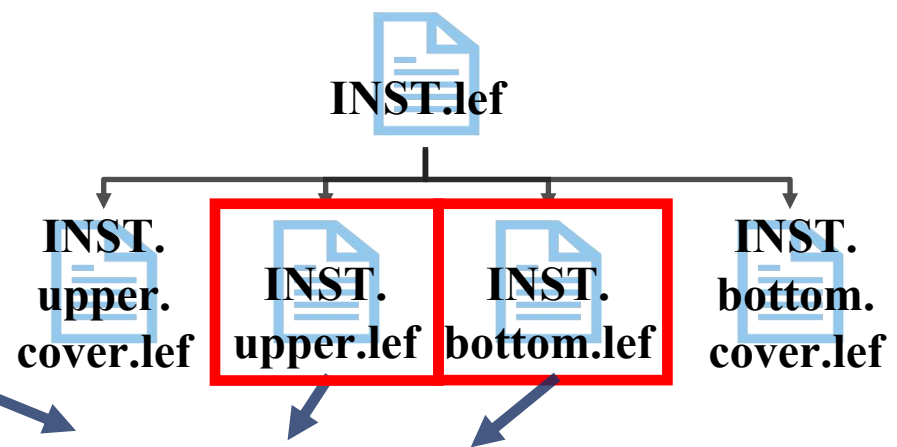


Homogeneous Integration: ASAP7 3D

M3_add (V)	V2_add
M2_add (H)	V1_add
M1_m (V)	V1_m
M2_m (H)	V2_m
M3_m (V)	V3_m
M4_m (H)	V4_m
M5_m (V)	V5_m
M6_m (H)	HB_layer
M7 (V)	V6
M6 (H)	V5
M5 (V)	V4
M4 (H)	V3
M3 (V)	V2
M2 (H)	V1
M1 (V)	

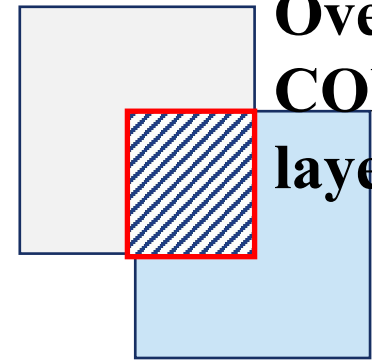
Upper CELL LEF

Bottom LEF CELL



**Build tier-specific physical masters:
upper.lef / bottom.lef (CORE Views)**

**However:
Overlaps Detected between
CORE cells on different
layers using 2D Tools**



Pin-3D Enablement (2/2): How to optimize one tier?

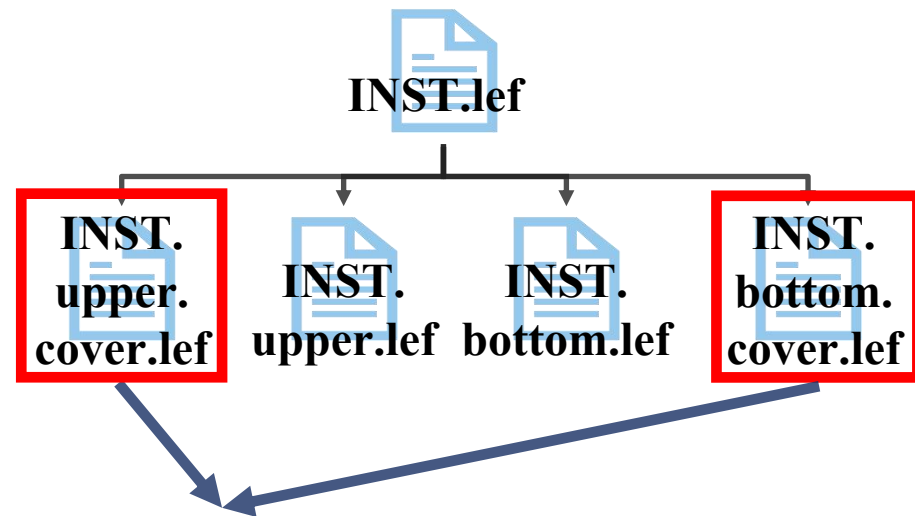


Homogeneous Integration: ASAP7 3D

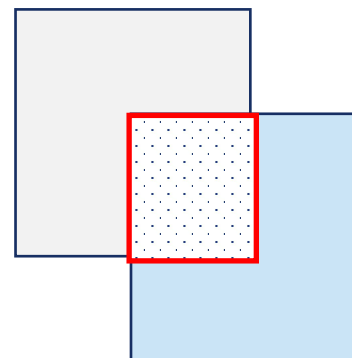
M3_add (V)	V2_add
M2_add (H)	V1_add
M1_m (V)	V1_m
M2_m (H)	V2_m
M3_m (V)	V3_m
M4_m (H)	V4_m
M5_m (V)	V5_m
M6_m (H)	HB_layer
M7 (V)	V6
M6 (H)	V5
M5 (V)	V4
M4 (H)	V3
M3 (V)	V2
M2 (H)	V1
M1 (V)	

Upper CELL LEF

Bottom LEF CELL



Use COVER views to make the opposite tier transparent, then FIX the hidden tier during optimization



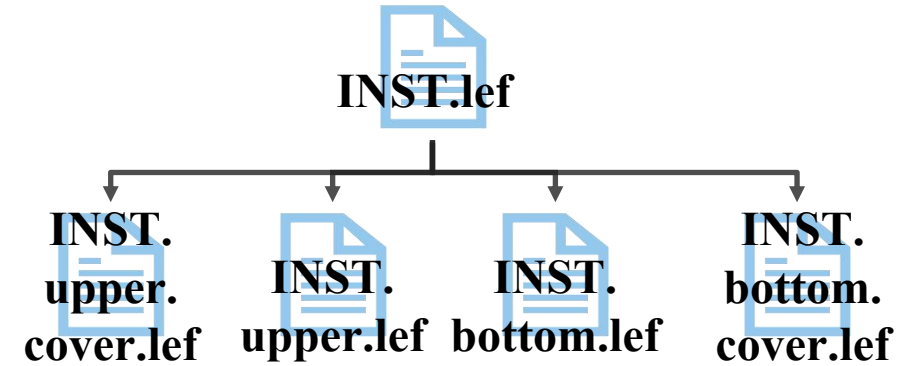
Overlaps will be ignored between COVER cells and CORE cells using 2D Tools

Pin-3D Enablement (2/2): How to optimize one tier?



Homogeneous Integration: ASAP7 3D

M3_add (V)	V2_add	Upper CELL LEF
M2_add (H)	V1_add	
M1_m (V)	V1_m	
M2_m (H)	V2_m	
M3_m (V)	V3_m	
M4_m (H)	V4_m	
M5_m (V)	V5_m	
M6_m (H)	HB_layer	
M7 (V)	V6	
M6 (H)	V5	
M5 (V)	V4	Bottom LEF CELL
M4 (H)	V3	
M3 (V)	V2	
M2 (H)	V1	
M1 (V)		

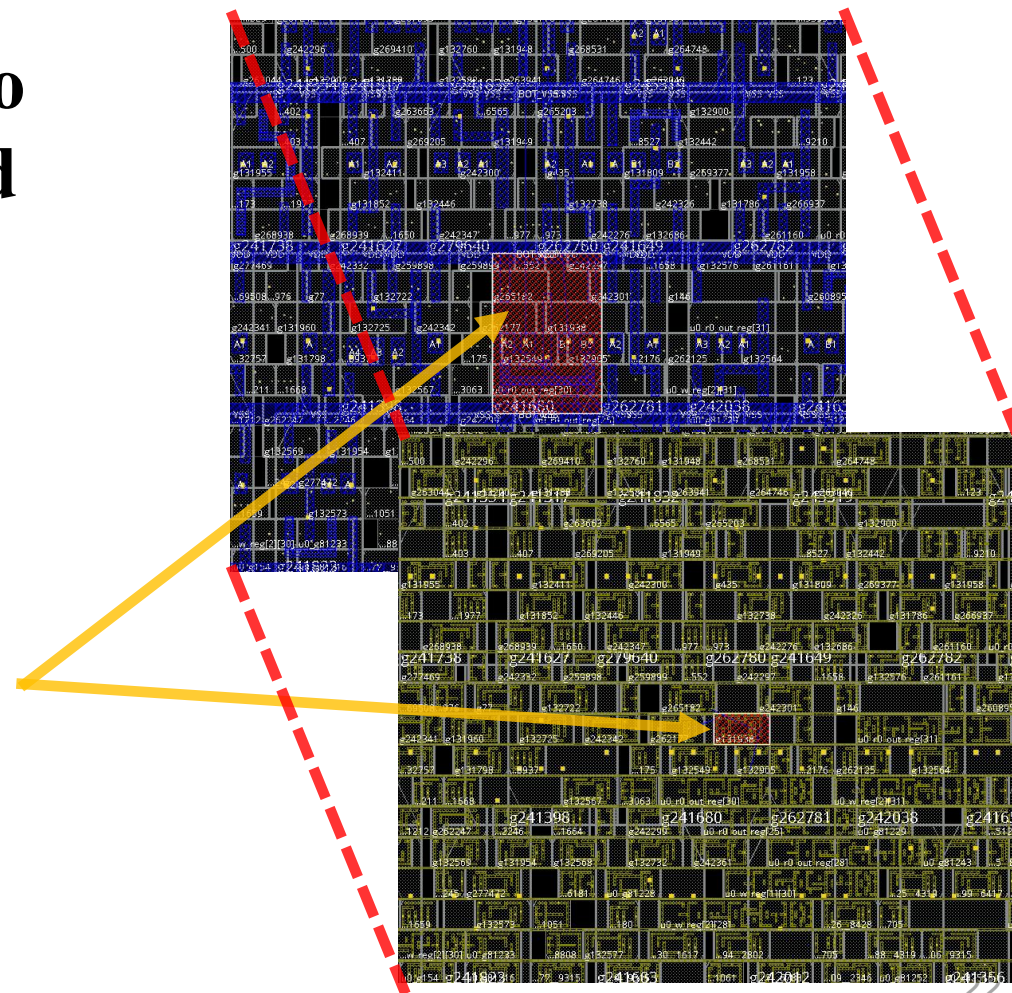


**To prevent unexpected cell insertion,
exclude the hidden tier using
DNU_CELL_FOR_UPPER /
DNU_CELL_FOR_BOTTOM**

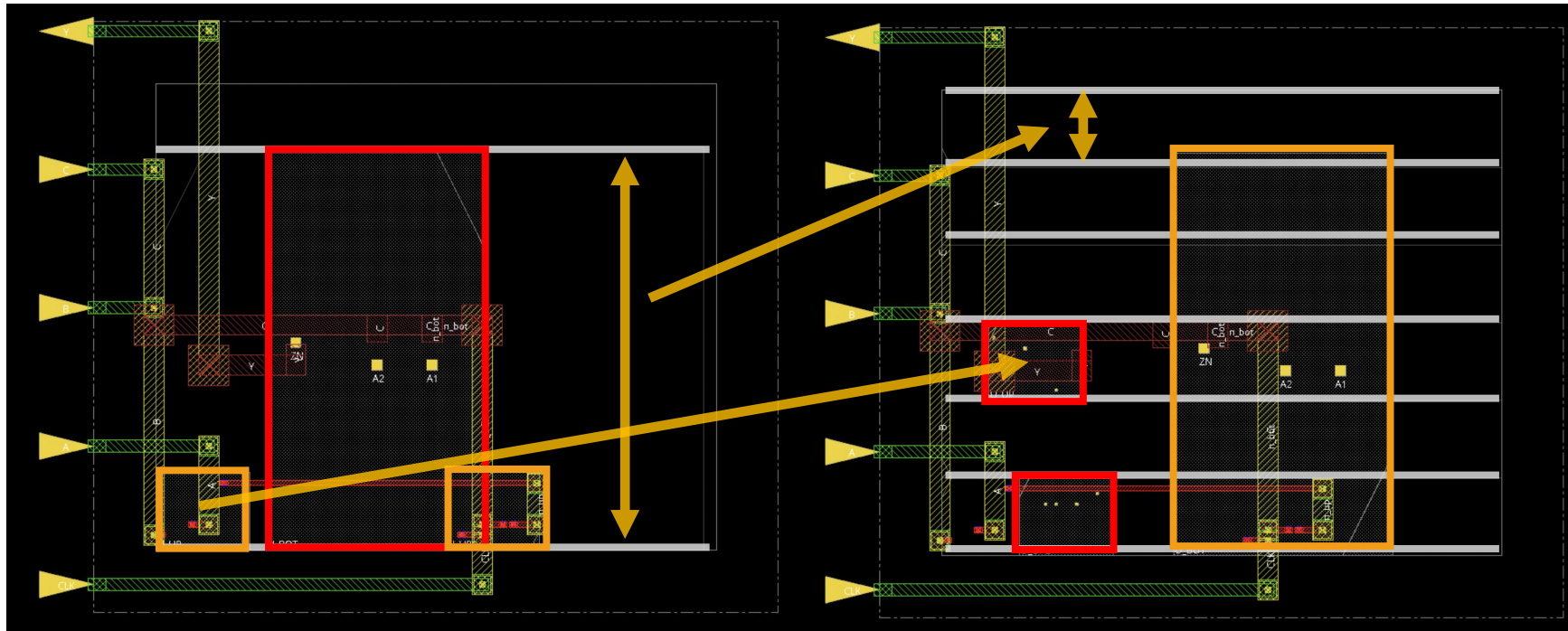
Tier Map for Cross-Die Cell Movement

For heterogeneous integration, we need a one-to-one cell mapping across libraries so that cells can move across tiers legally and consistently.

- **Site legality:** row, PDN, orientation, etc.
- **Physical/Logical:** physical pin, area map, logical function map, etc.



For tier legalization: Reconstruct rows



Site Bottom & Place Design

Site Upper & Place Design

- Heterogeneous cells have different **height** and different **site definitions / row constraints**.
- We **reconstruct rows** when activating a tier to ensure standard 2D placers can run legalization across mixed PDKs.

Pin-3D Flow: Step-by-Step Execution Flow

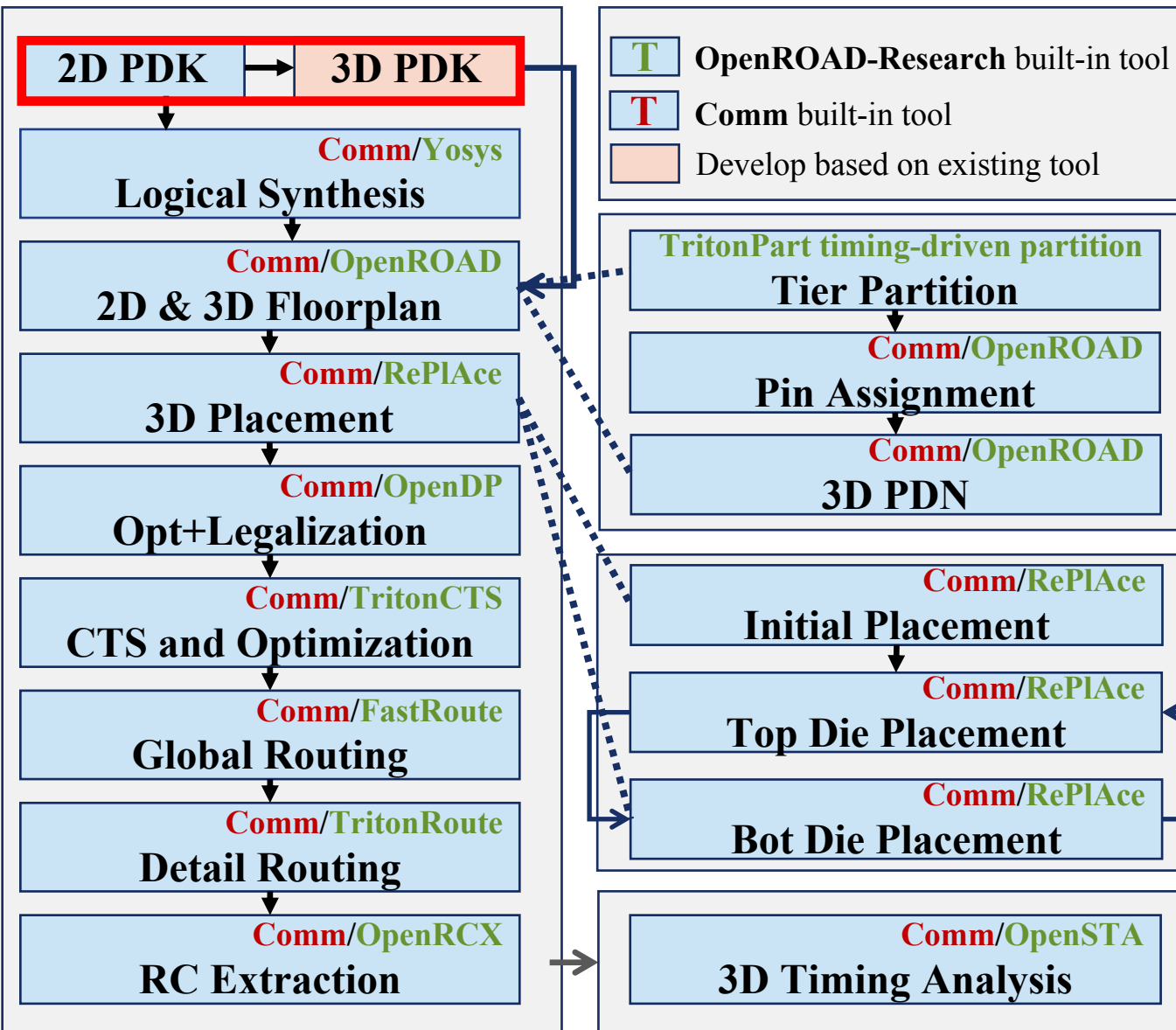


What we mentioned above:

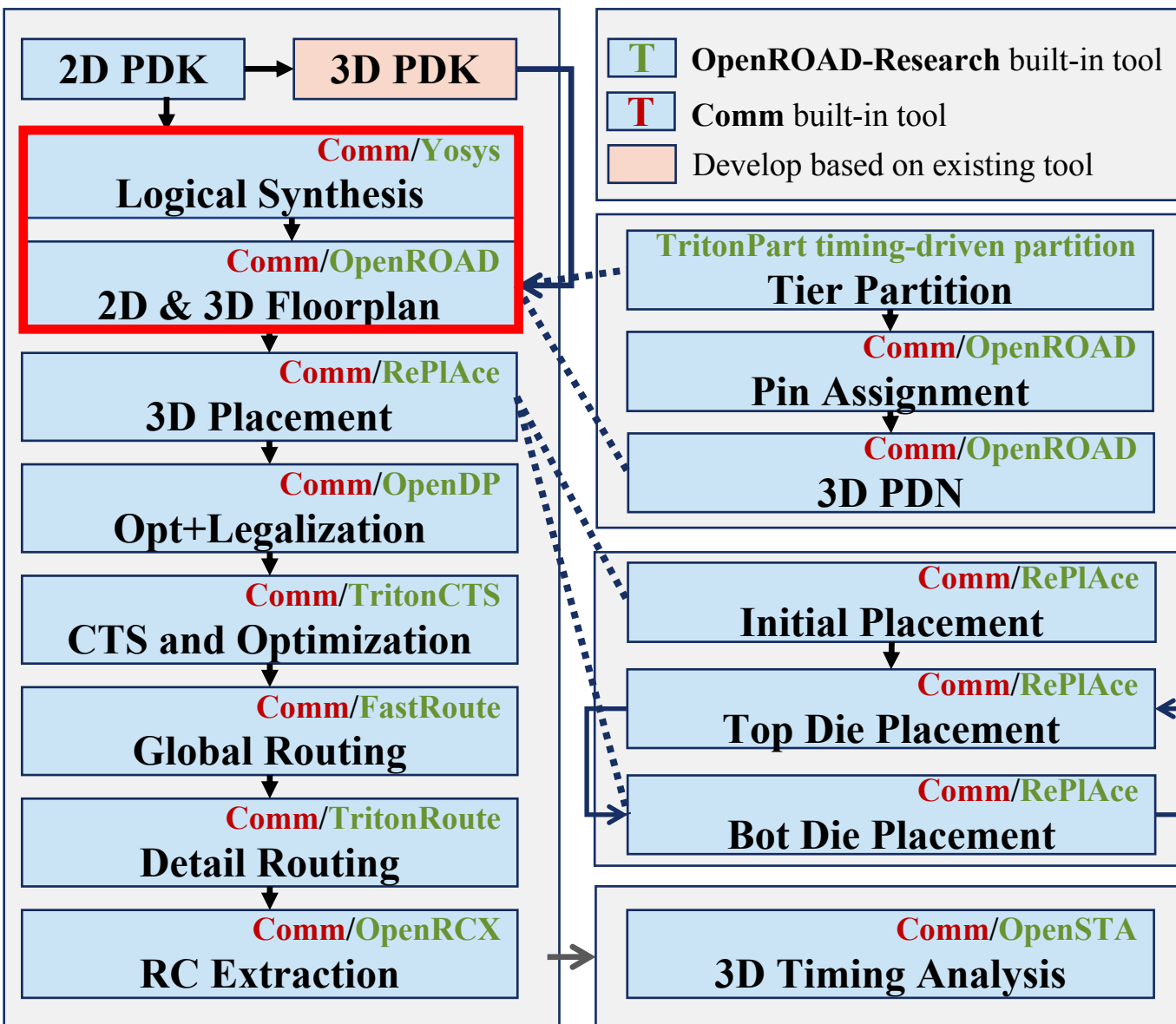
- 2D → 3D PDK & tier-strategy
- 3 PDKs:
 - NG45_3D
 - ASAP7_3D
 - ASAP7 + NanGate45

Now we are introducing:

- A fully automated RTL-to-GDS flow for F2F 3D stacks by reusing mature 2D engines



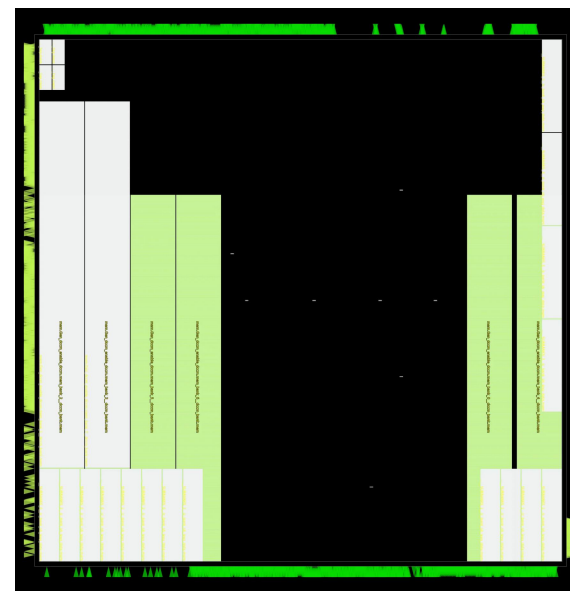
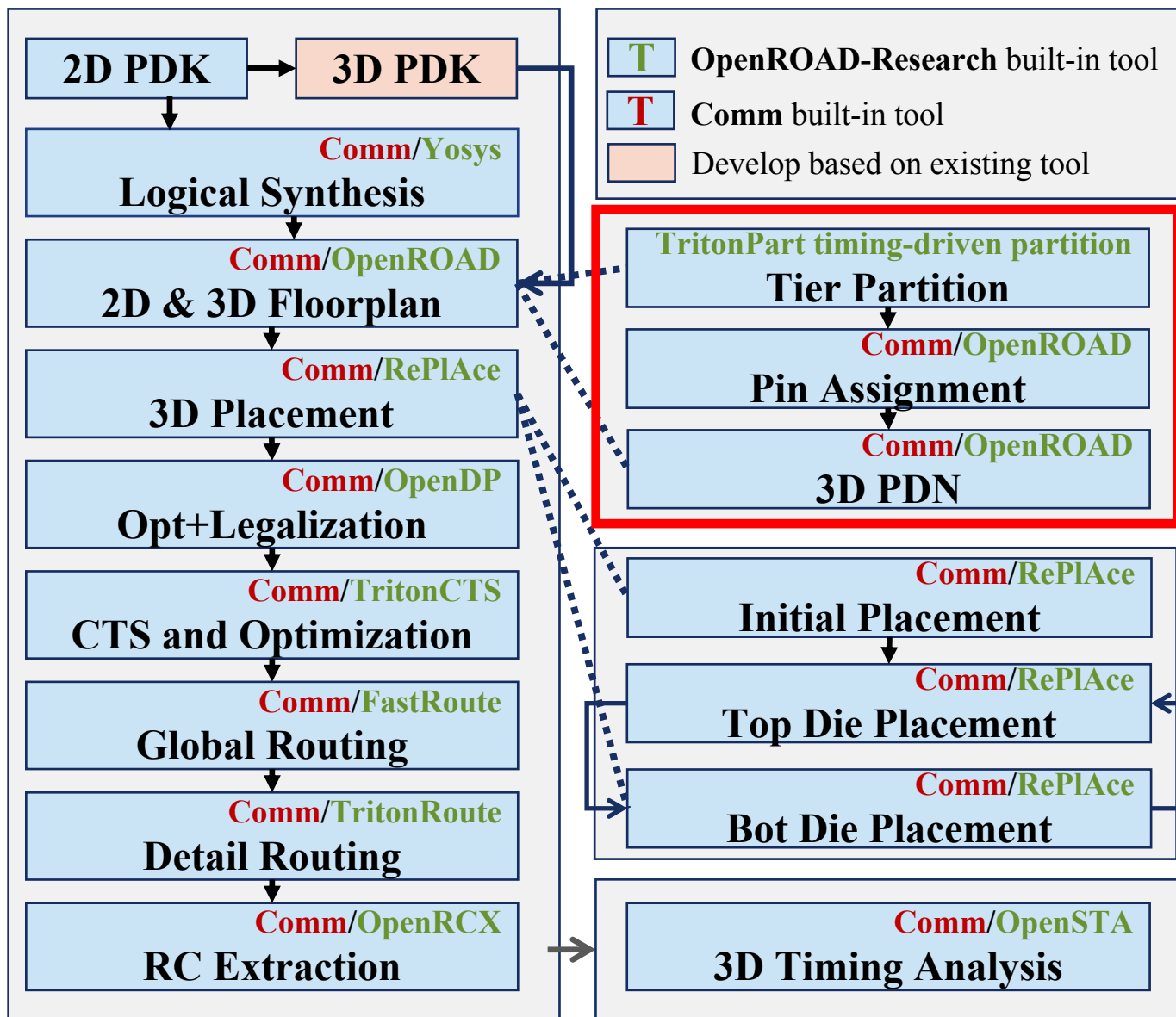
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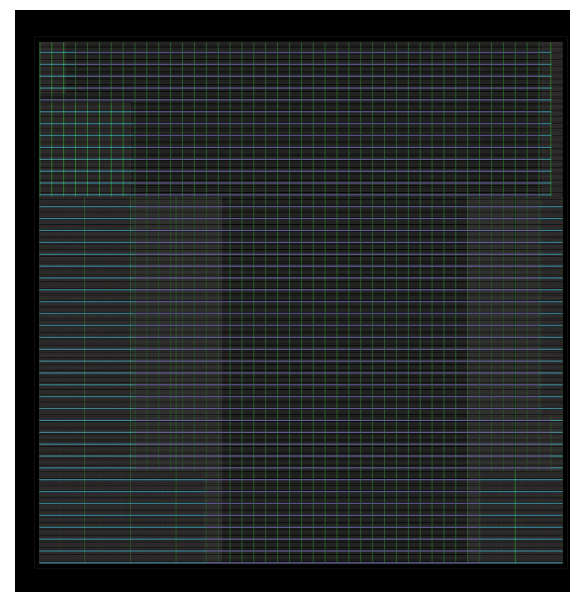
**2D logical synthesis
using 2D PDK**

Partition First with TritonPart

Pin-3D Flow: Step-by-Step Execution Flow

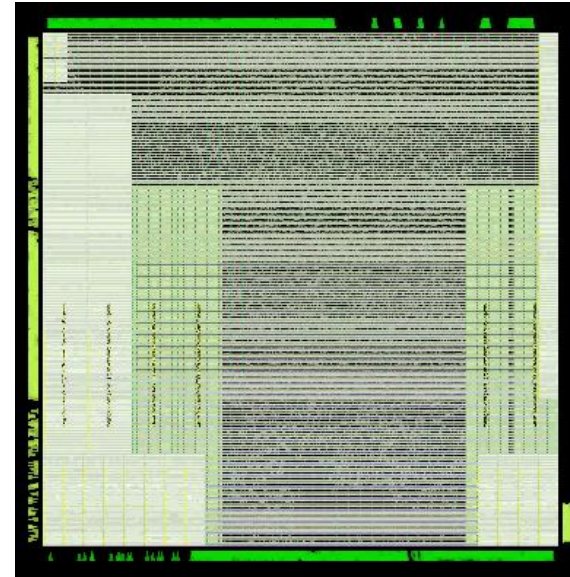
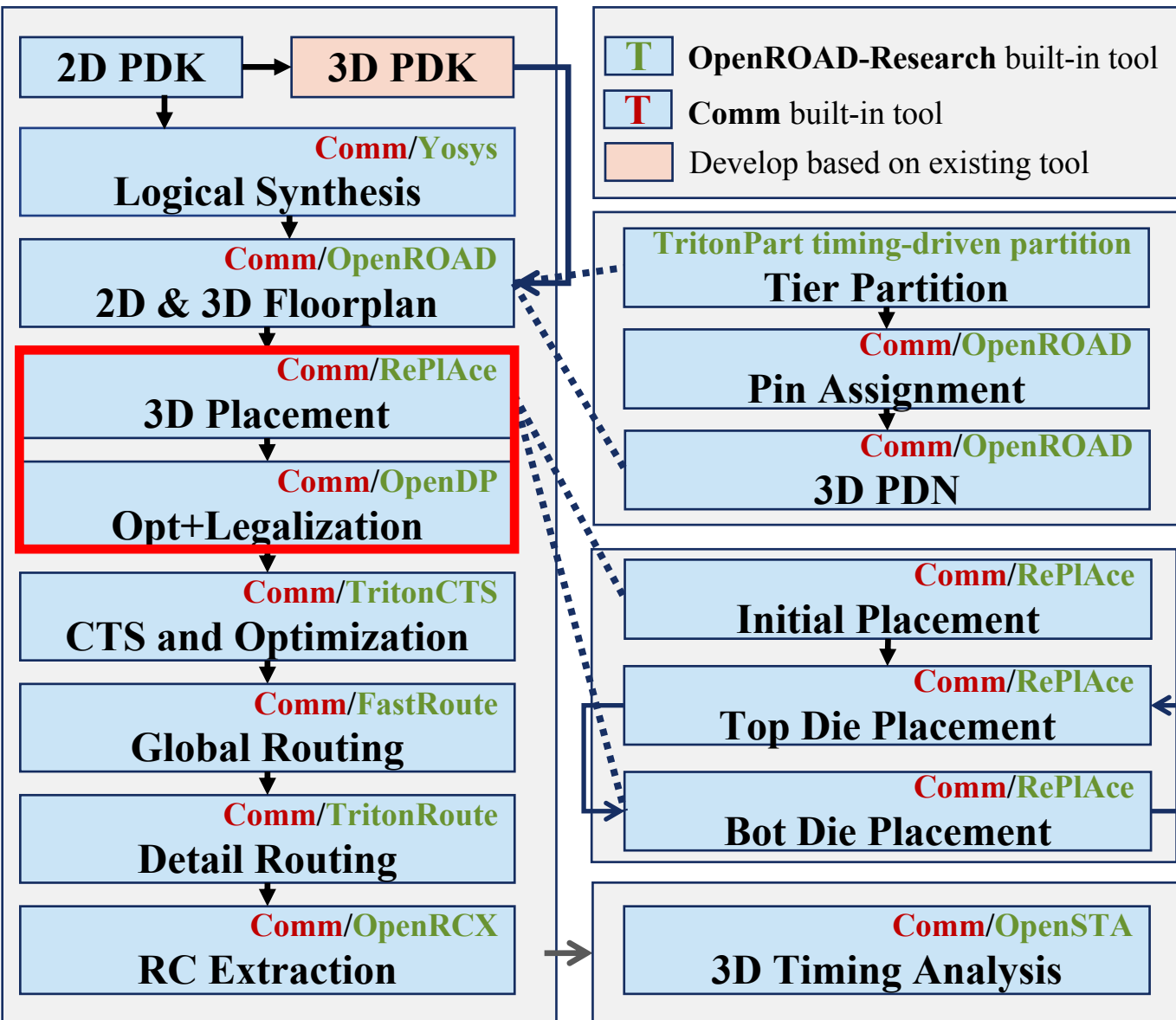


Macro Place

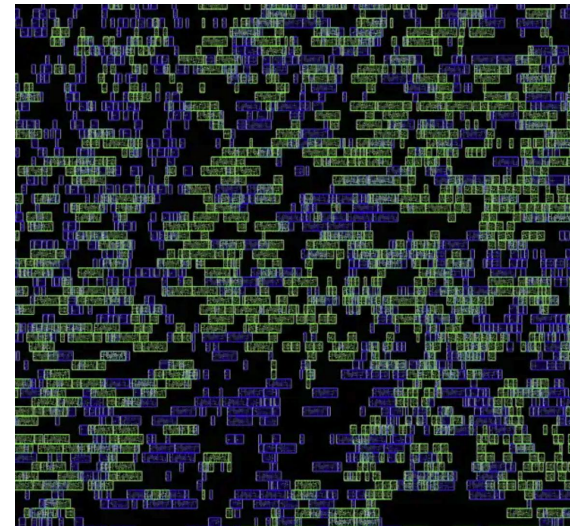


PDN

Pin-3D Flow: Step-by-Step Execution Flow

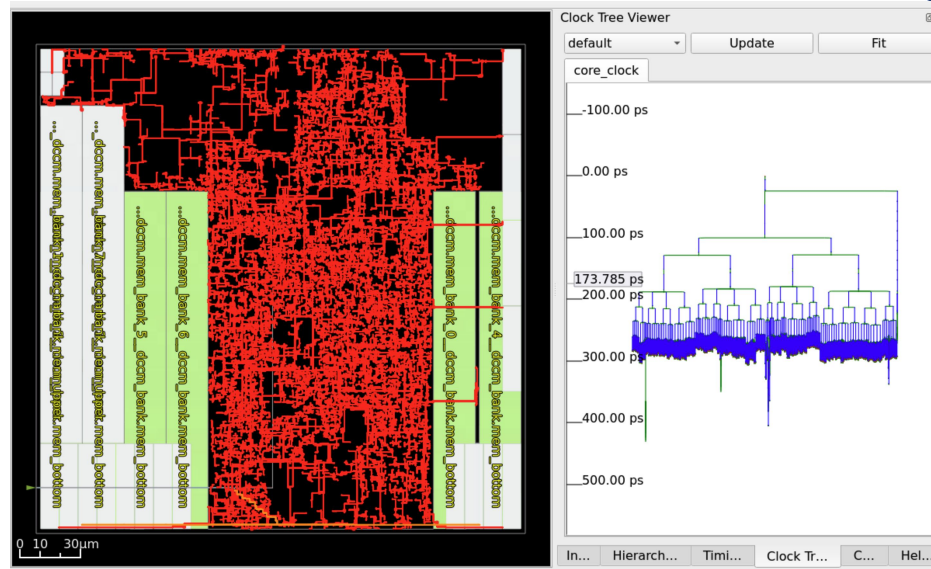
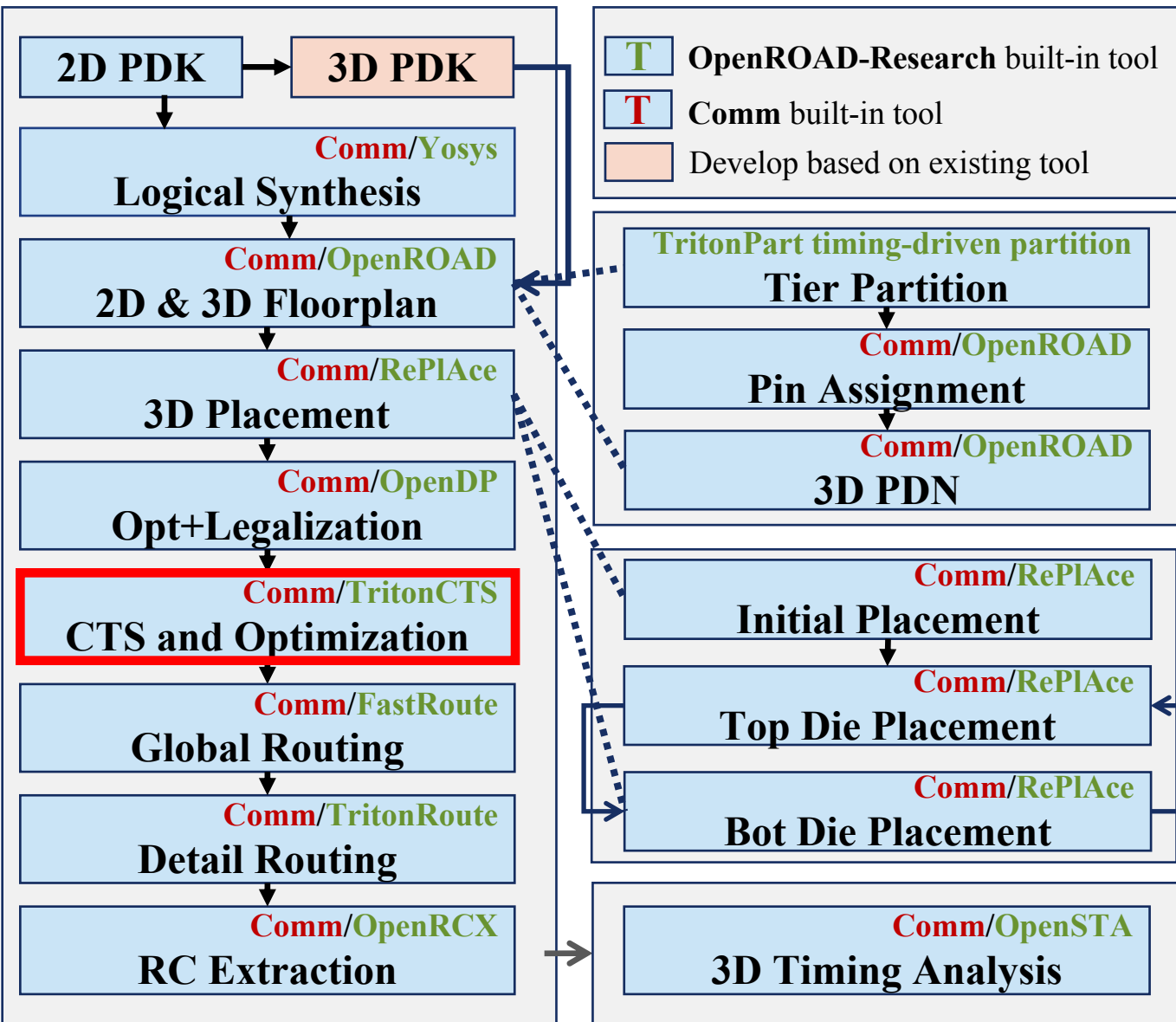


Global Place

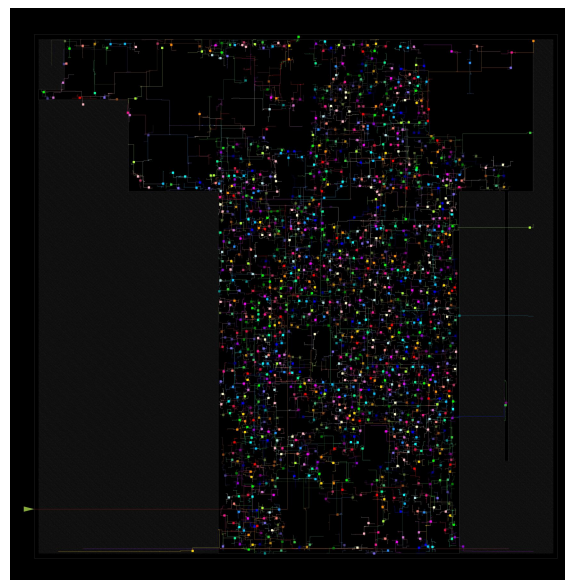


Opt + Legalize

Pin-3D Flow: Step-by-Step Execution Flow

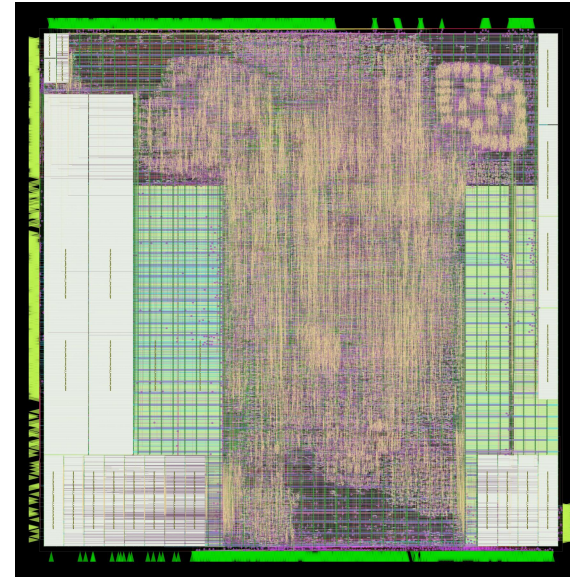
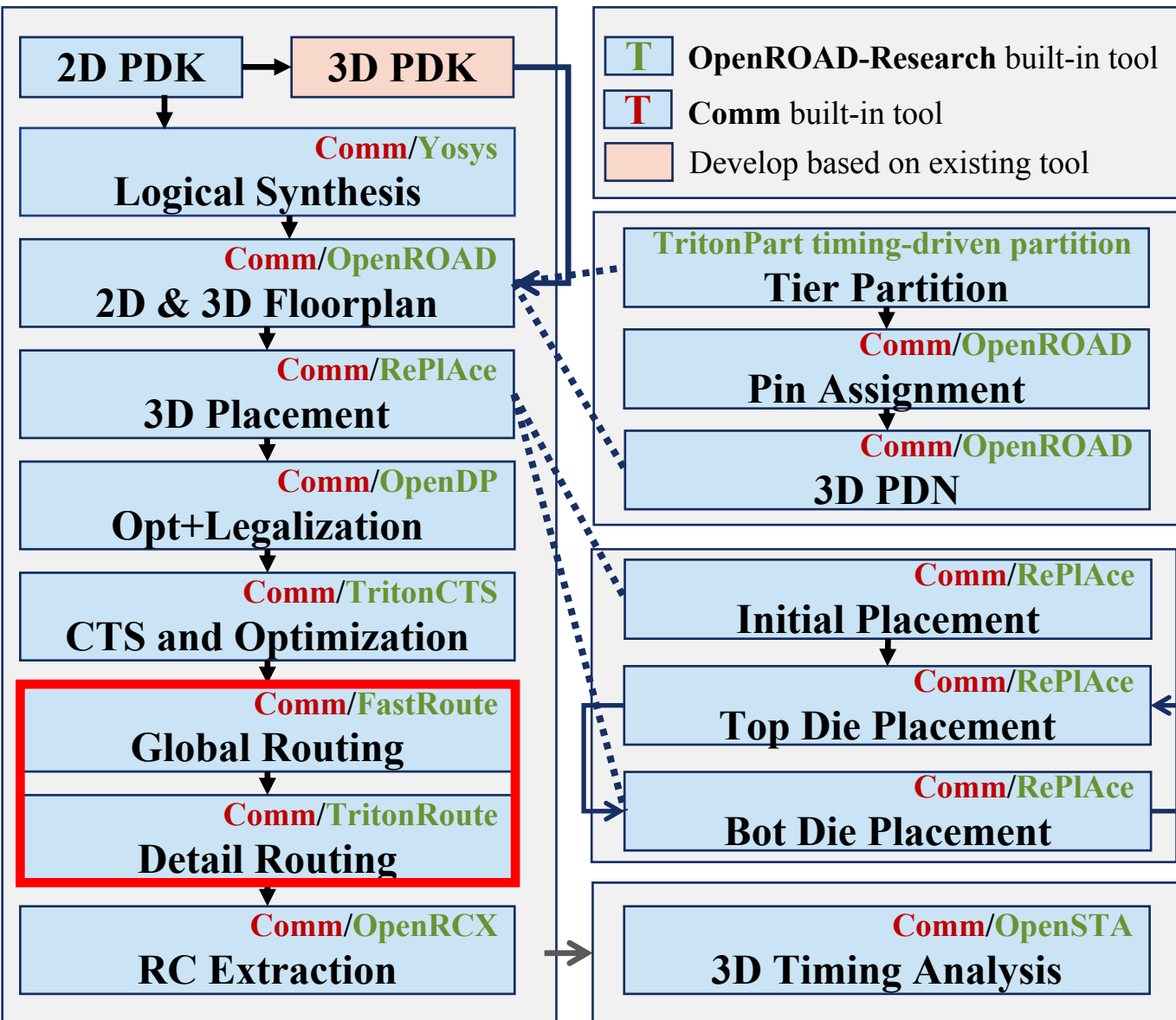


CTS

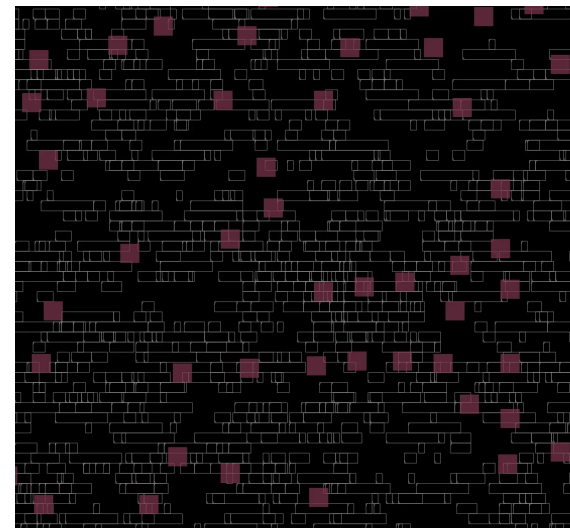


Clock Net

Pin-3D Flow: Step-by-Step Execution Flow



Routed layout



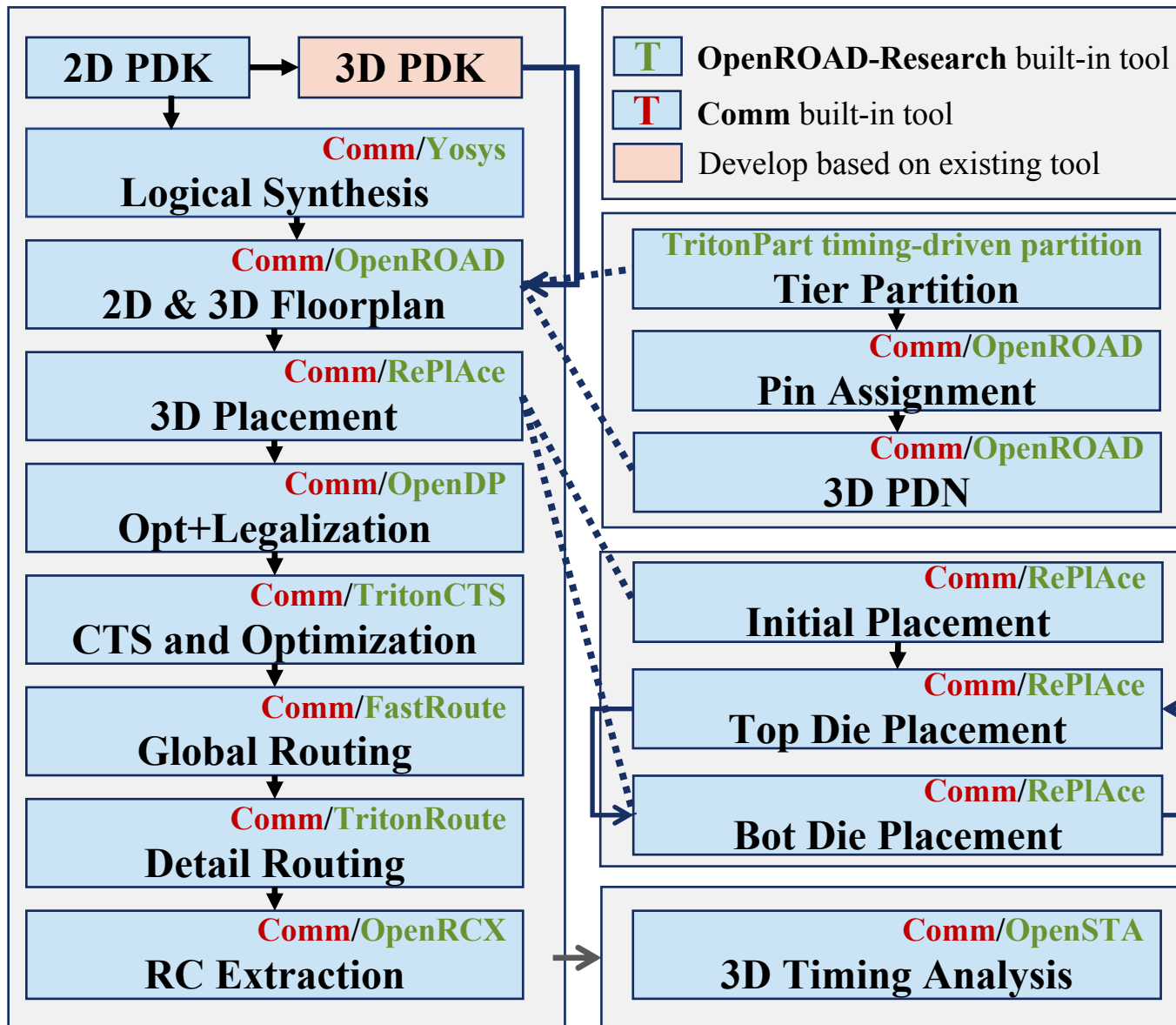
HBTs

Pin-3D Flow: Step-by-Step Execution Flow



Handoff Outline:

- Read and write .v and .def, use .lef and .lib to mark different tier cell master
- Synthesis → 1_synth.{v,sdc}
- 2D Floorplan + IO → 2_2_floorplan_io.{v,def}
- Partition → partition.txt → DEF/Verilog → DESIGN_NAME_3D.fp.{v,def}
- 3D Floorplan → 2_floorplan.{v,def,sdc}
- 3D Placement → 3_placed.{v,def,sdc}
- CTS → 4_cts.{def,v,sdc}
- Routing → 5_route.{def,v,sdc}
- Eval → post-route STA/RC extraction

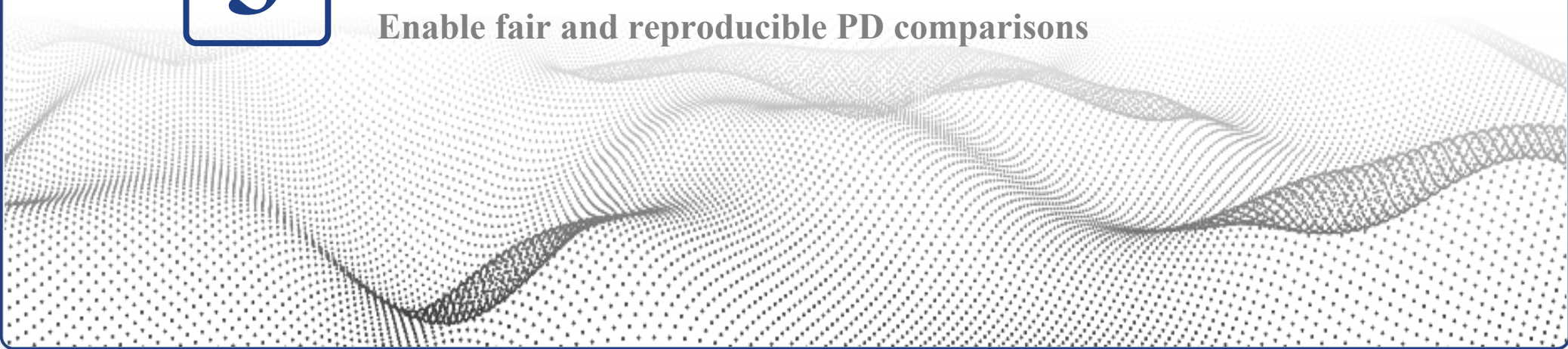




3

Pin-3D Validations

Enable fair and reproducible PD comparisons



Mixed flow: The "Synthesis Gap"



(Detailed Routing: fixed at 20 iterations for runtime)

Toolchain Configuration (Synthesis + Backend)	StdCell Area (μm^2)	Power (mW)	rWL (mm)	WNS (ns)	DRVs	FEPs	HBT
Commercial Synthesis + Commercial Backend	16,446.5	20.33	232.2	-0.016	3	6	904
Commercial Synthesis + OpenROAD Placement + Commercial CTS/Routing	16,510.1	22.50	237.5	-0.040	0	54	1,031
Commercial Synthesis + OpenROAD Backend	16,193.3	24.58	209.8	-0.135	153	144	522
Yosys Synthesis + Commercial Backend	17,604.7	38.77	195.2	0.012	0	0	982
Yosys Synthesis + Commercial Placement + OpenROAD CTS/Routing	17,664.3	45.25	189.7	-0.094	0	87	915
Yosys Synthesis + OpenROAD Backend	18,100.8	46.33	193.4	-0.064	8	55	650

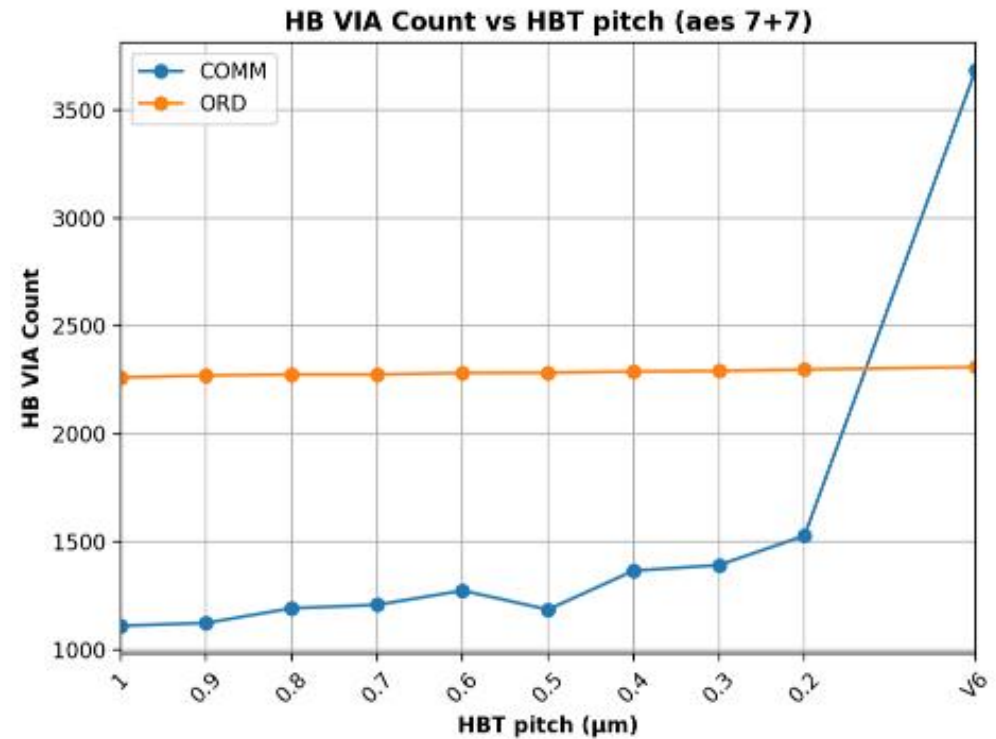
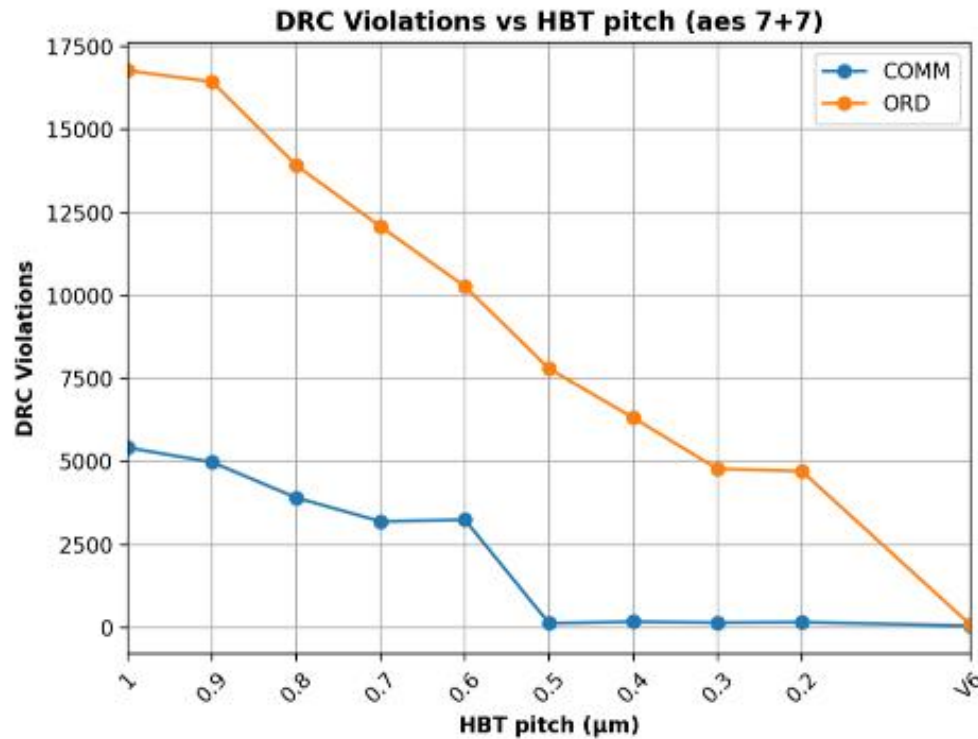
❑ Mixed flow: The "Routing & CTS Gap"



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Effect on HBT Pitch size



With a larger pitch, HBTs lead to more shorts and spacing issues.

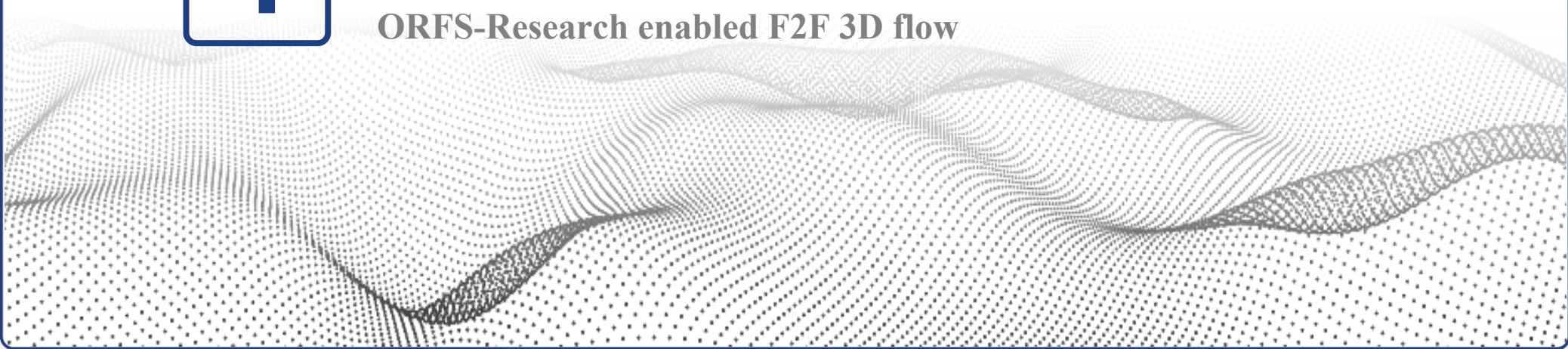
As the pitch becomes closer to via-scale, these violations drop quickly.



4

Key Takeaway

ORFS-Research enabled F2F 3D flow



Why This Flow Matters (Beyond Any Single QoR Number)



Problem Addressed

Reproducibility gap:

missing PDK details and fragile scripts make results hard to reproduce.



Core Value

Explicit evaluation contract:

consistent stage I/O and metrics, even when tools are swapped.



Community Impact

Drop-in extensibility:

plug in a new tool without rebuilding the RTL-to-GDS pipeline.

Key Takeaway

A maintained, audit-ready benchmarking harness making 3D PD research **reproducible**, **comparable**, and **extensible**.

<https://github.com/ieee-ceda-datc/ORFS-Research/tree/maple/pin3Dflow/flow-Pin3D>

QR code for our ORFS-Research Pin 3D



ORFS-Research maple/pin3Dflow (legacy)



<https://github.com/CODA-Team/TaiWei-Pin-3D>